molex

Part Number: 878030122

Product Description : 1.00mm Pitch DDR-2 DIMM Socket, 25 Degree Angle, Through Hole, 1.8V Voltage Key, 2.79mm Tail Length, 0.76µm Gold (Au) Plating, 240 Circuits, Natural (Off White) Latch, Lead-Free

Series Number: 87803

Status: Obsolete

Product Category: Memory Module Connectors



Documents & Resources

EE-87803-001-001.pdf

SP-87803-001-001.zip

Specifications

PS-87803-003-001.pdf

Product Environment Compliance

Compliance

GADSL/IMDS	Not Relevant
China RoHS	e per SJ/T 11365-2006
EU ELV	Not Relevant
Low-Halogen Status	Not Low-Halogen per IEC 61249-2-21
REACH SVHC	Not Contained per D(2025)4165-DC (25 June 2025)
EU RoHS	Compliant per EU 2015/863

Compliance Statements

- EU RoHS
- REACH SVHC
- Low-Halogen

Industry Documents

- IPC 1752A Class C
- IPC 1752A Class D
- Molex Product Compliance Declaration

- IEC-62474
- chemSHERPA (xml)

<u>Substances of Interest</u>

PFAS

EU RoHS Certificate of Compliance

Additional Product Compliance Information

Part Details

General

Status	Obsolete
Category	Memory Module Connectors
Series	87803
Description	1.00mm Pitch DDR-2 DIMM Socket, 25 Degree Angle, Through Hole, 1.8V Voltage Key, 2.79mm Tail Length, 0.76µm Gold (Au) Plating, 240 Circuits, Natural (Off White) Latch, Lead-Free
Comments	Lubricant at the contact
Component Type	Socket
JEDEC Outline	MO-237
Product Name	DDR2 DIMM
UPC	822350158718

Agency

CSA	LR19980
UL	E29179

Electrical

Current - Maximum per Contact	0.5A
Voltage Key	1.8V, Center
Voltage - Maximum	30V AC (RMS)/DC

Physical

Circuits (Loaded)	240
Circuits (maximum)	240

Durability (mating cycles max)	25
Entry Angle	25° Angle
Flammability	94V-0
Housing Color	Black
Keying to Mating Part	Yes
Latch Color	Natural (Off-White)
Material - Metal	Copper Alloy
Material - Plating Mating	Gold
Material - Plating Termination	Tin
Material - Resin	High Temperature Thermoplastic
Net Weight	11.298/g
Packaging Type	Tray
PCB Locator	Yes
PCB Retention	Yes
PCB Thickness - Recommended	1.60mm
PC Tail Length	2.79mm
Pitch - Mating Interface	1.00mm
Plating min - Mating	0. 762μm
Plating min - Termination	2.540μm
Temperature Range - Operating	-55° to +85°C
Termination Interface Style	Through Hole

Solder Process Data

Max-Duration	5
Lead-Free Process Capability	SMC&WAVE
Max- <mark>Cyc</mark> le	2
Max-Temp	260

Mates With / Use With

Mates with Part(s)

Description	Part Number
Mates With	JEDEC Standard 1.27mm Modules